

74HC4020; 74HCT4020

14-stage binary ripple counter

Rev. 6 — 3 February 2016

Product data sheet

1. General description

The 74HT4020; 74HCT4020 is a 14-stage binary ripple counter with a clock input (CP), an overriding asynchronous master reset input (MR) and 12 buffered parallel outputs (Q0, and Q3 to Q13). The counter advances on the HIGH-to-LOW transition of CP. A HIGH on MR clears all counter stages and forces all outputs LOW, independent of the state of CP. Each counter stage is a static toggle flip-flop. This device features reduced input threshold levels to allow interfacing to TTL logic levels. Inputs also include clamp diodes, this enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Wide supply voltage range from 2.0 V to 6.0 V
- Input levels:
 - ◆ For 74HC4020: CMOS level
 - ◆ For 74HCT4020: TTL level
- Multiple package options
- Complies with JEDEC standard no. 7A
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Applications

- Frequency dividing circuits
- Time delay circuits
- Control counters

4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC4020D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT4020D				
74HC4020DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT4020DB				



Table 1. Ordering information ...continued

Type number	Package			Version
	Temperature range	Name	Description	
74HC4020PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT4020PW				
74HC4020BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
74HCT4020BQ				

5. Functional diagram

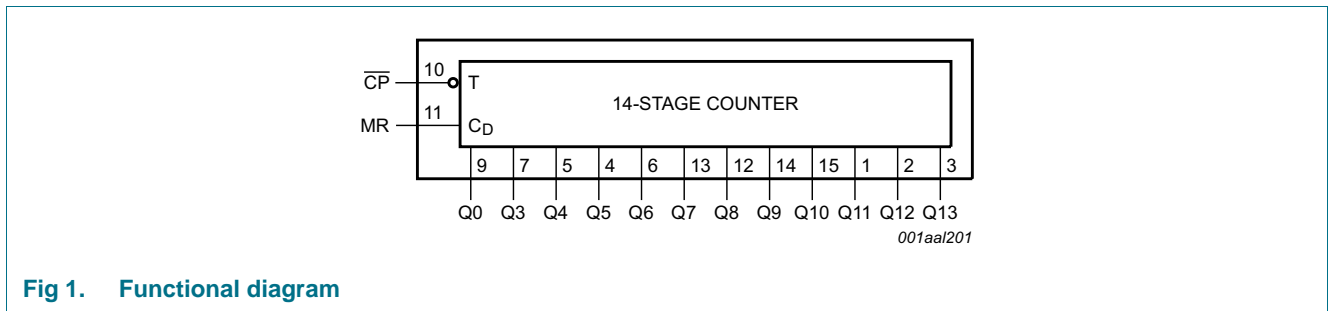


Fig 1. Functional diagram

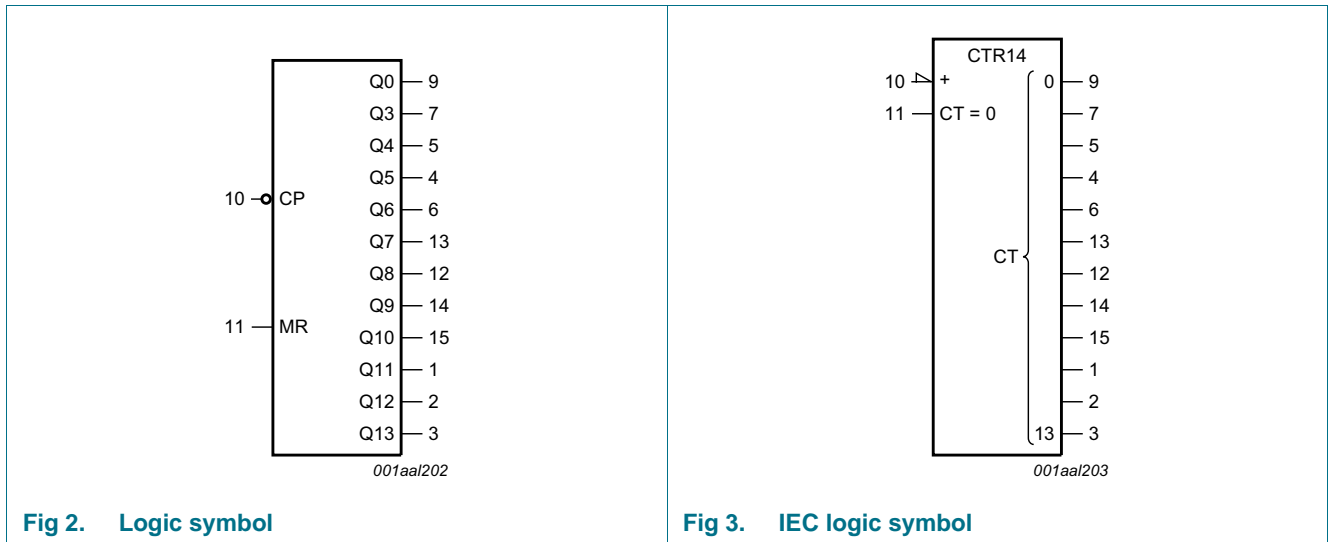


Fig 2. Logic symbol

Fig 3. IEC logic symbol

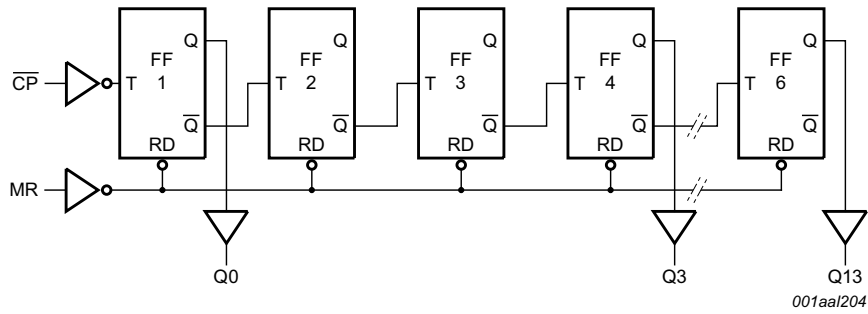


Fig 4. Logic diagram

6. Pinning information

6.1 Pinning

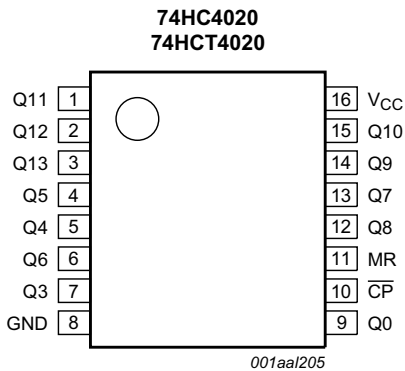
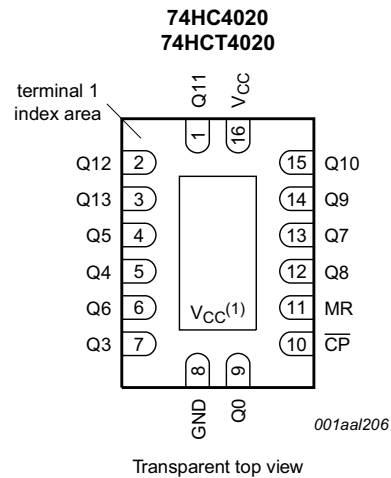


Fig 5. Pin configuration SO16, SSOP16 and TSSOP16



- (1) The substrate is attached to this pad using conductive die attach material. It cannot be used as supply pin or input. It is recommended that no connection is made at all.

Fig 6. Pin configuration DHVQFN16

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Q0, Q3 to Q13	9, 7, 5, 4, 6, 13, 12, 14, 15, 1, 2, 3	output
GND	8	ground (0 V)
CP	10	clock input (HIGH-to-LOW, edge-triggered)
MR	11	master reset input (active HIGH)
VCC	16	positive supply voltage

7. Functional description

Table 3. Function table

Input		Output
CP	MR	Q0, Q3 to Q13
↑	L	no change
↓	L	count
X	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; ↑ = LOW-to-HIGH clock transition; ↓ = HIGH-to-LOW clock transition.

7.1 Timing diagram

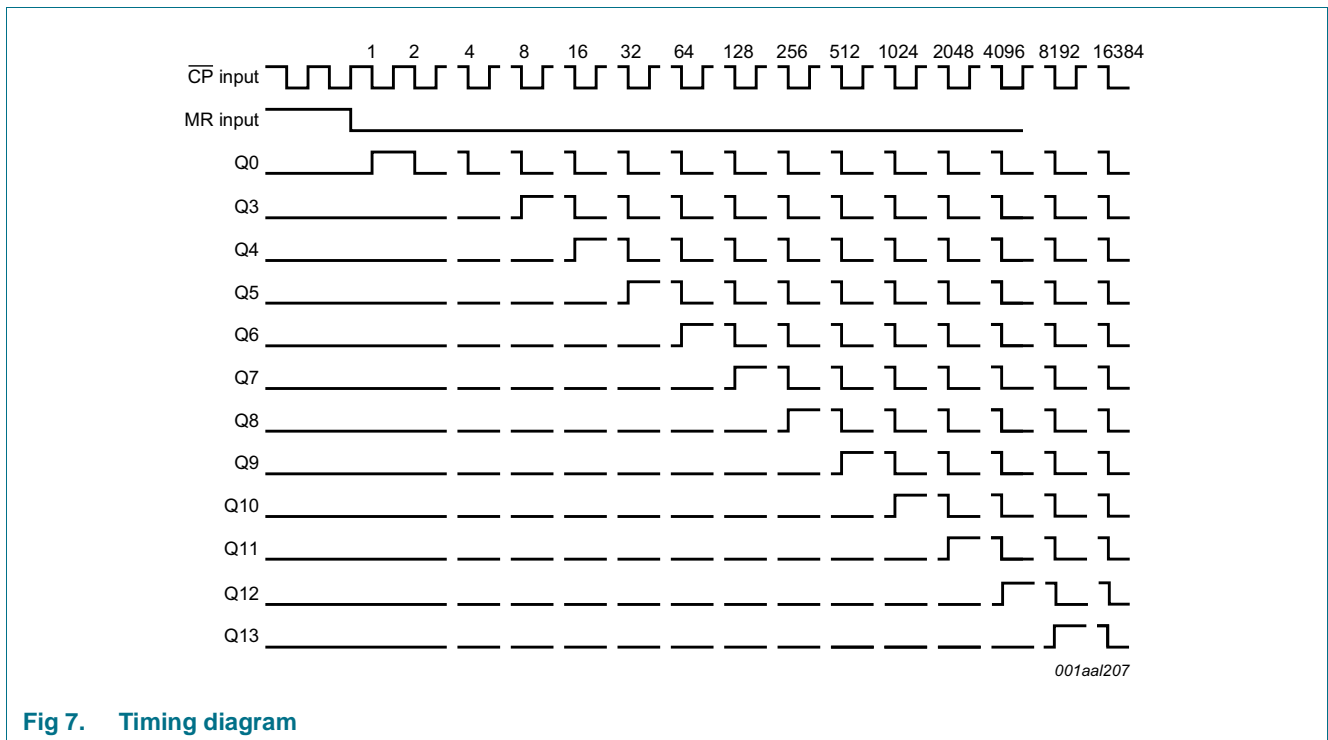


Fig 7. Timing diagram

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	-	±20	mA
I _{OK}	output clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	-	±20	mA
I _O	output current	-0.5 V < V _O < V _{CC} + 0.5 V	-	±25	mA
I _{CC}	supply current		-	±50	mA
I _{GND}	ground current		-	±50	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C [1]			
		SO16, SSOP16, TSSOP16 and DHVQFN16 packages	-	500	mW

- [1] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.
 For SSOP16 and TSSOP16 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.
 For DHVQFN16 package: P_{tot} derates linearly with 4.5 mW/K above 60 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	74HC4020			74HCT4020			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	0	-	V _{CC}	V
Δt/ΔV	input transition rise and fall rate	except for Schmitt trigger inputs							
		V _{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V _{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	-	-	-	ns/V
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C

10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC4020										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = -20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
		I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	-
C _I	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT4020										
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
V _{OL}	LOW-level output voltage	I _O = -4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
		V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
I _I	input leakage current	I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.1	-	±1	-	±1	μA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 2.1 V; I _O = 0 A; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V								
		pin MR	-	110	396	-	495	-	539	μA
		pin CP	-	85	306	-	383	-	417	μA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

11. Dynamic characteristics

Table 7. Dynamic characteristics

GND (ground = 0 V); C_L = 50 pF unless otherwise specified; for test circuit, see [Figure 10](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC4020										
t _{pd}	propagation delay	CP to Q0; see Figure 8 ^[1]								
		V _{CC} = 2.0 V; C _L = 50 pF	-	39	140	-	175	-	210	ns
		V _{CC} = 4.5 V; C _L = 50 pF	-	14	28	-	35	-	42	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	11	-	-	-	-	-	ns
		V _{CC} = 6.0 V; C _L = 50 pF	-	11	24	-	30	-	36	ns
		Q _n to Q _{n+1} ; see Figure 9								
		V _{CC} = 2.0 V; C _L = 50 pF	-	22	75	-	95	-	110	ns
		V _{CC} = 4.5 V; C _L = 50 pF	-	8	15	-	19	-	22	ns
t _{PHL}	HIGH to LOW propagation delay	V _{CC} = 5.0 V; C _L = 15 pF	-	6	-	-	-	-	-	ns
		V _{CC} = 6.0 V; C _L = 50 pF	-	6	13	-	16	-	19	ns
		MR to Q _n ; see Figure 8								
		V _{CC} = 2.0 V; C _L = 50 pF	-	55	170	-	215	-	225	ns
t _t	transition time	V _{CC} = 4.5 V; C _L = 50 pF	-	20	34	-	43	-	51	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	17	-	-	-	-	-	ns
		V _{CC} = 6.0 V; C _L = 50 pF	-	16	29	-	37	-	43	ns
		Q _n ; see Figure 8 ^[2]								
t _t	transition time	V _{CC} = 2.0 V; C _L = 50 pF	-	19	75	-	95	-	110	ns
		V _{CC} = 4.5 V; C _L = 50 pF	-	7	15	-	19	-	22	ns
		V _{CC} = 6.0 V; C _L = 50 pF	-	6	13	-	16	-	19	ns

Table 7. Dynamic characteristics ...continued
 GND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 10](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_W	pulse width	\overline{CP} HIGH or LOW; see Figure 8								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	80	14	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	16	4	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V; $C_L = 50$ pF	14	3	-	17	-	20	-	ns
		MR HIGH; see Figure 8								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	16	6	-	20	-	24	-	ns
t_{rec}	recovery time	MR to \overline{CP} ; see Figure 8								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	50	6	-	65	-	75	-	ns
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	10	2	-	13	-	15	-	ns
		$V_{CC} = 6.0$ V; $C_L = 50$ pF	9	2	-	11	-	13	-	ns
f_{max}	maximum frequency	see Figure 8								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	6.0	30	-	4.8	-	4.0	-	MHz
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	30	92	-	24	-	20	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	101	-	-	-	-	-	MHz
		$V_{CC} = 6.0$ V; $C_L = 50$ pF	35	109	-	28	-	24	-	MHz
C_{PD}	power dissipation capacitance	[3]	-	19	-	-	-	-	-	pF

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t_{pd}	propagation delay	\overline{CP} to Q0; see Figure 8 [1]								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	18	36	-	45	-	54	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
		Qn to Qn+1; see Figure 9								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	8	15	-	19	-	22	ns
t_{PHL}	HIGH to LOW propagation delay	$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	22	45	-	56	-	68	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	19	-	-	-	-	-	ns
t_t	transition time	Qn; see Figure 8 [2]								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	7	15	-	19	-	22	ns
t_W	pulse width	\overline{CP} HIGH or LOW; see Figure 8								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	20	7	-	25	-	30	-	ns
		MR HIGH; see Figure 8								
t_{rec}	recovery time	$V_{CC} = 4.5$ V; $C_L = 50$ pF	20	8	-	25	-	30	-	ns
		MR to \overline{CP} ; see Figure 8								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	10	2	-	13	-	15	-	ns

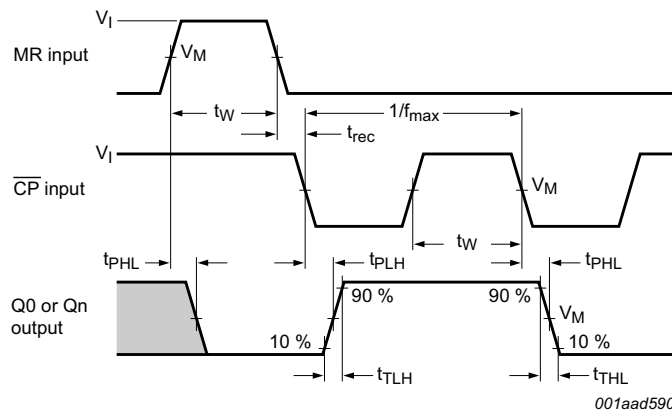
Table 7. Dynamic characteristics ...continued

GND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 10](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
f_{max}	maximum frequency	see Figure 8								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	25	47	-	20	-	17	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	52	-	-	-	-	-	MHz
C_{PD}	power dissipation capacitance	[3]	-	20	-	-	-	-	-	pF

- [1] t_{pd} is the same as t_{PHL} and t_{PLH} .
- [2] t_t is the same as t_{THL} and t_{TLH} .
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μ W).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V.

12. Waveforms



Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 8. Clock timing, propagation delays, pulse widths and measurement points

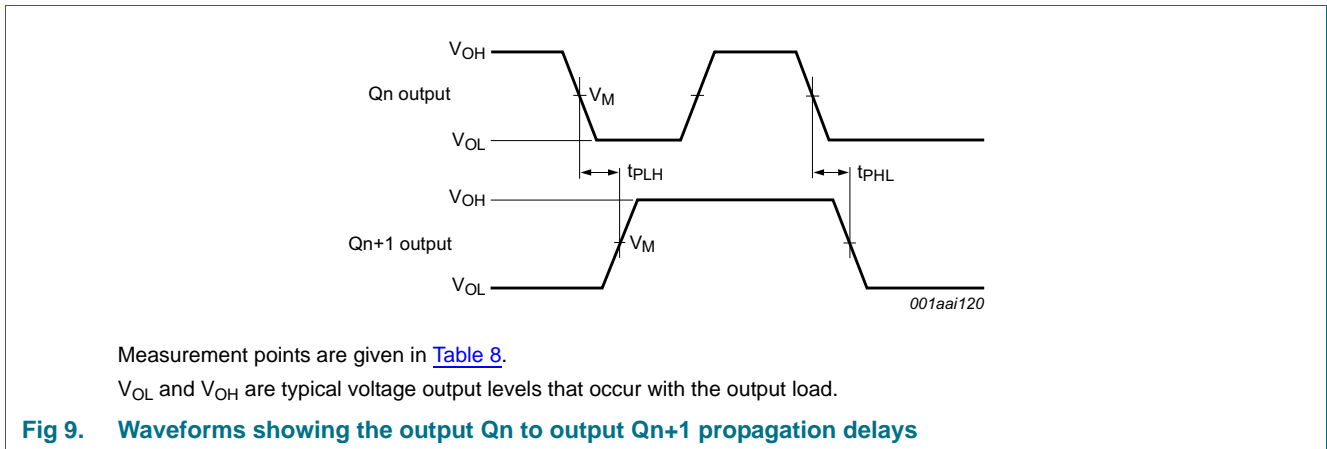


Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74HC4020	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74HCT4020	1.3 V	1.3 V

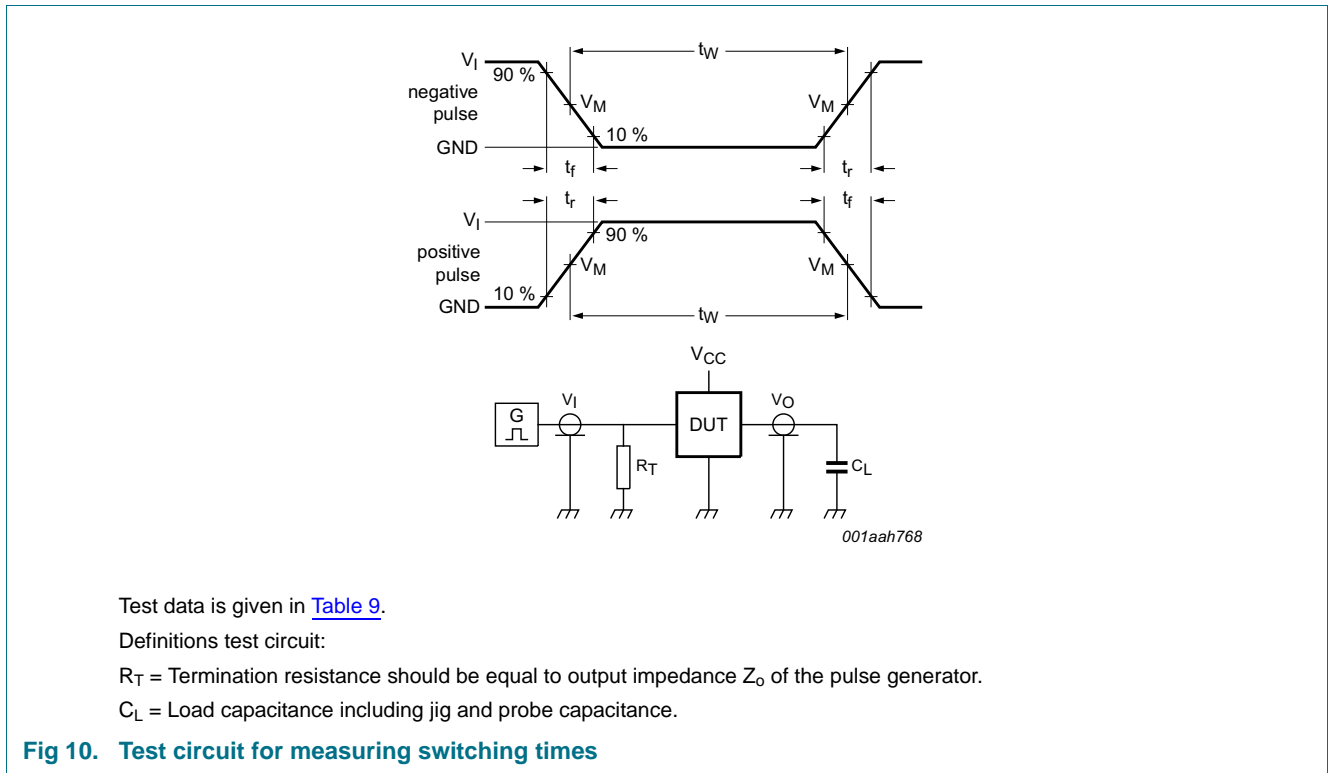


Table 9. Test data

Type	Input		Load
	V_I	t_r, t_f	C_L
74HC4020	V_{CC}	6 ns	15 pF, 50 pF
74HCT4020	3 V	6 ns	15 pF, 50 pF

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

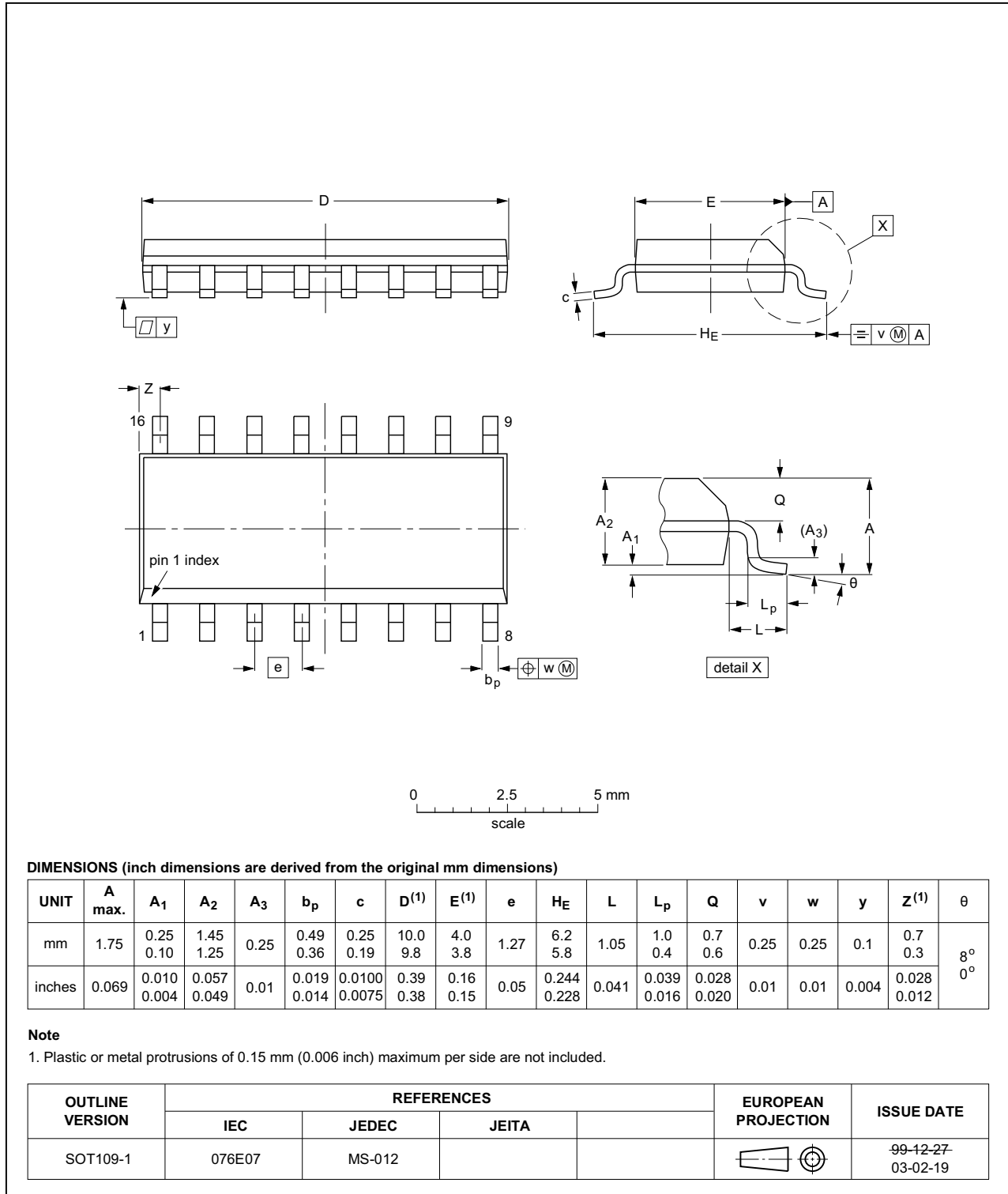


Fig 11. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

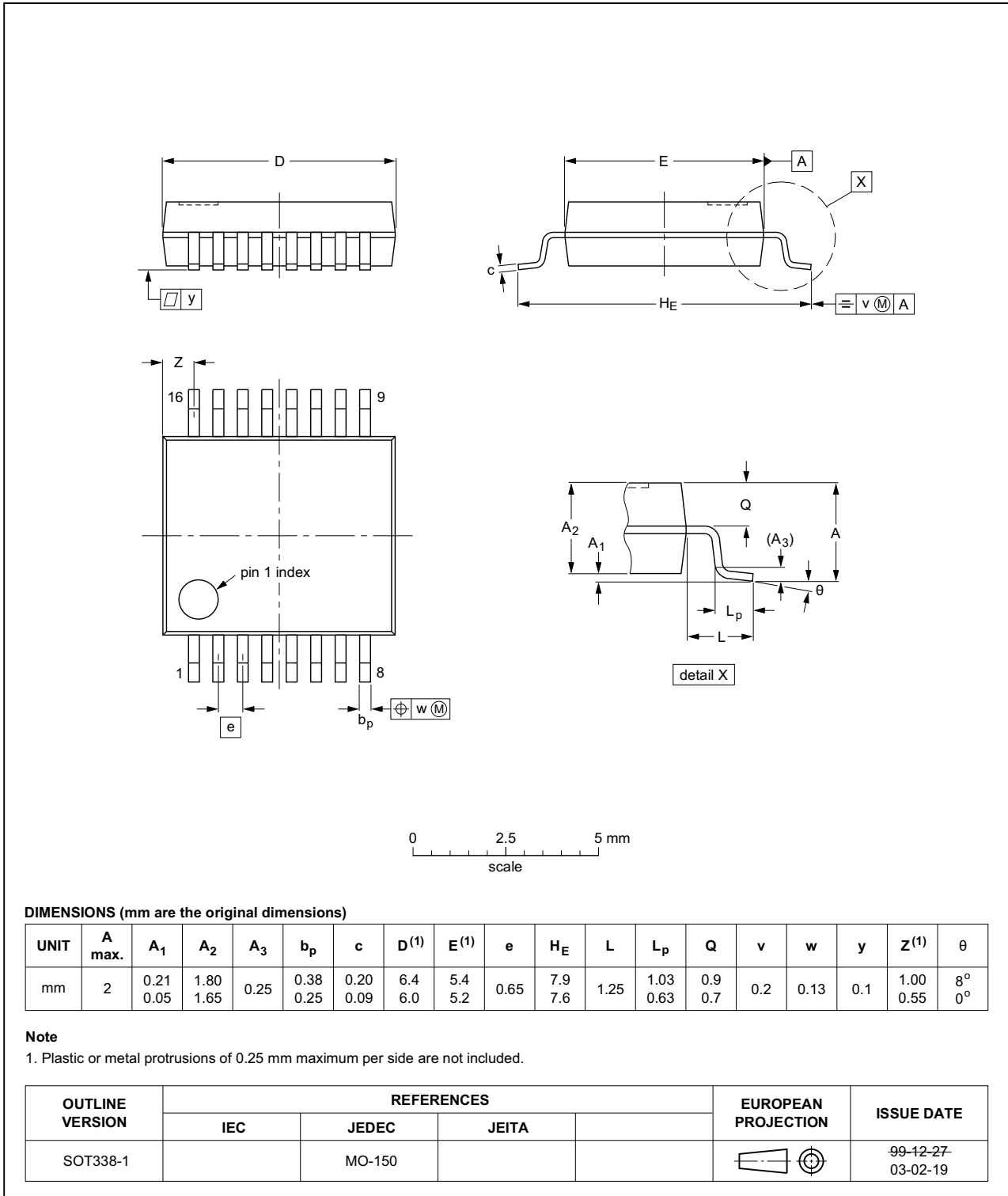


Fig 12. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

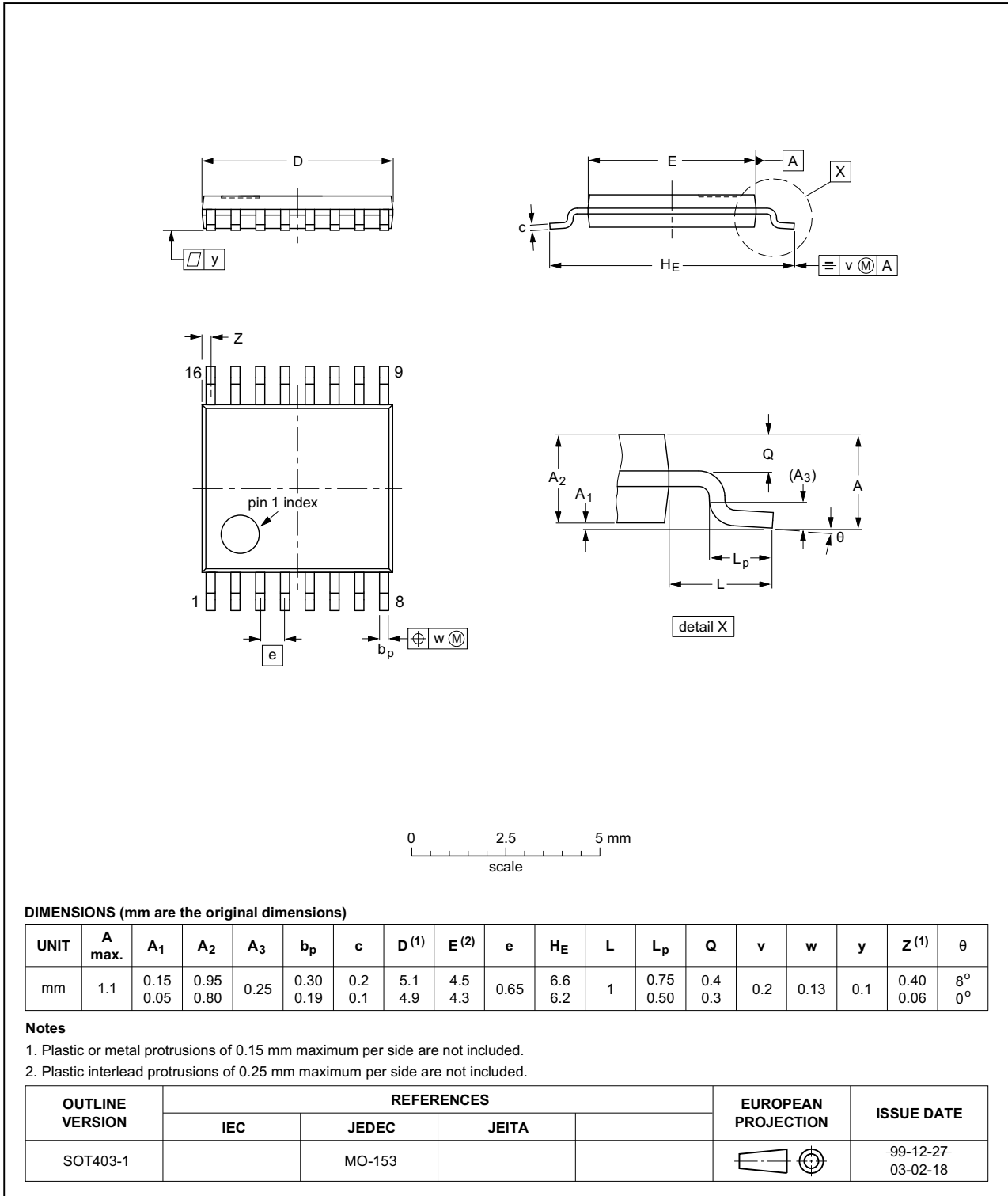


Fig 13. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

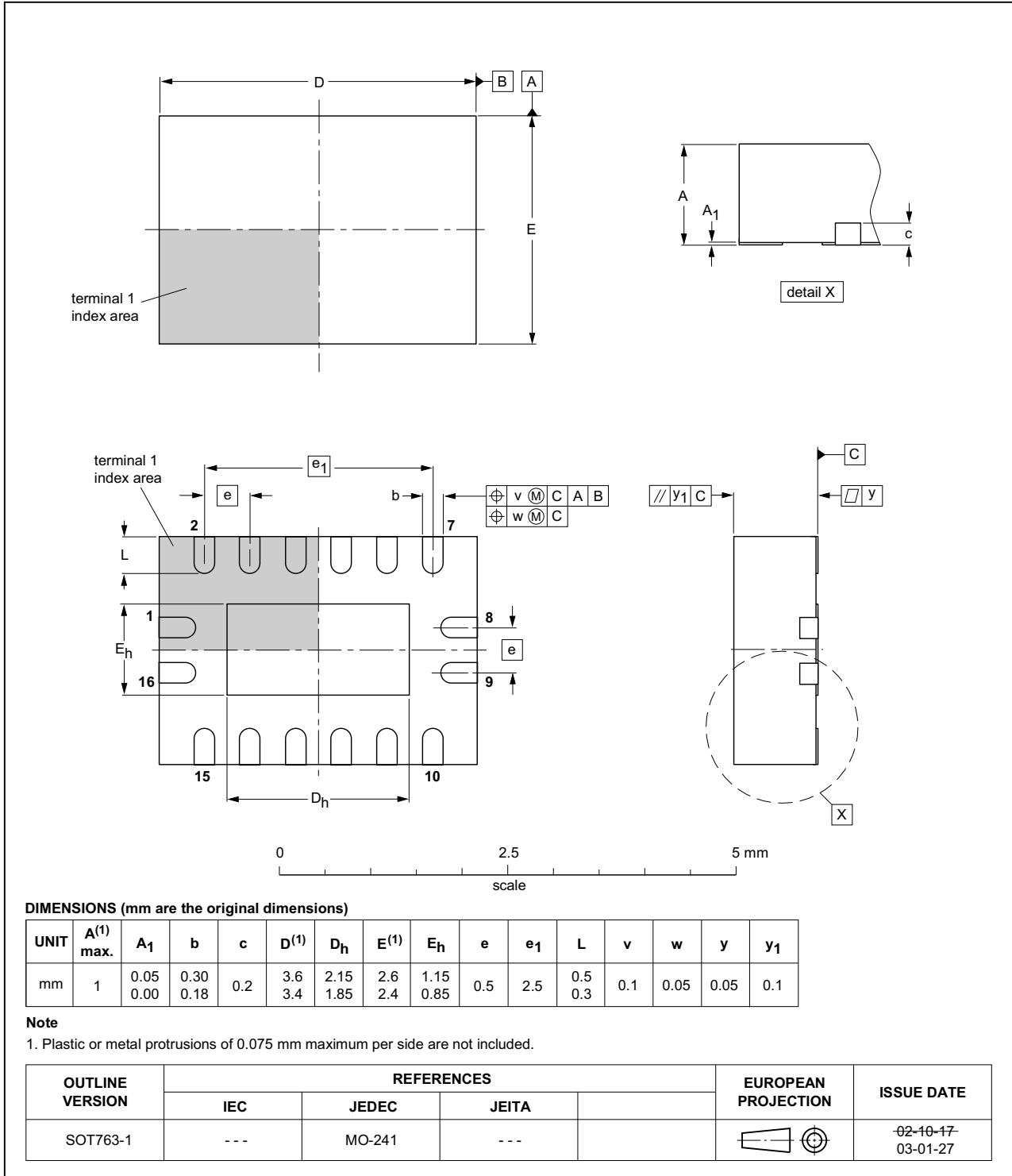


Fig 14. Package outline SOT763-1 (DHVQFN16)

14. Abbreviations

Table 10. Abbreviations

Acronym	Abbreviation
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4020 v.6	20160203	Product data sheet	-	74HC_HCT4020 v.5
Modifications:	<ul style="list-style-type: none"> Type numbers 74HC4020N and 74HCT4020N (SOT38-4) removed. 			
74HC_HCT4020 v.5	20120806	Product data sheet	-	74HC_HCT4020 v.4
Modifications:	<ul style="list-style-type: none"> Measurement points added to figure 8 (errata). 			
74HC_HCT4020 v.4	20111213	Product data sheet	-	74HC_HCT4020 v.3
Modifications:	<ul style="list-style-type: none"> Legal pages updated. 			
74HC_HCT4020 v.3	20100120	Product data sheet	-	74HC_HCT4020_CNV v.2
74HC_HCT4020_CNV v.2	19970901	Product specification	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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